

FIRST CLASS MAIL

Handbook 18 (File Ahead of Section 7C)  
Temporary Instruction  
Western Electric Company, Inc.  
Installation Engineering - Kearny

Section T.I. - 7C

2-17-67

CONNECTING - SOLDER LUGS, PUNCHINGS AND SPLICES

DRESS OF LUGS AND TREATMENT OF LUGS AT BATTERY POSTS AND WET CEMF CELLS

1. GENERAL

1.1 It is a present practice to dip solderless lugs in a sealing compound when they terminate at battery posts and wet CEMF cells. Solderless lugs are considered pressure type and are covered in Section 7D, however, the Bell Telephone Laboratories feel at this time that all types of lugs terminating at battery posts and wet CEMF cells should be protected with a sealing compound. All types include, not only pressure type covered in Section 7D, but solder type covered in this Section and compression type used in Electronic Switching Systems. (Compression type are those connectors compressed on to the wire mechanically or hydraulically). Since Handbook 18 has no appropriate section for compression type lugs, sealing information is now included in Sections 7C and 7D until such section is written.

1.2 Along with the above sealing information a paragraph has been added concerning forming and dressing lugs within enclosures, under covers or behind barriers.

2. INSTRUCTION

2.1 After Paragraph 5.41, add the following:

5.42 Taped lugs within enclosures, under covers or behind barriers shall be formed and dressed so as to prevent undue pressures from metal edges and corners and contained so as not to interfere with closure of doors, placement of covers, barriers, etc.

5.5 Sealing Lugs Connected to Wet Cell Batteries and Wet CEMF Cells

5.51 All types of lugs to be connected directly to alkaline type (wet) CEMF cells, or to battery posts, or to details which in turn are connected directly to CEMF Cells or battery posts, shall be treated as follows:

5.511 After the wire is secured to the lug and no further forming is required, immerse the lug in one of the following compounds to a distance of about 1/2" above the end of the lead insulation:

1st Choice - Clear Varnish RM-647622

2nd Choice - Acid Resistant Enamel RM-646317

The contact surface of the lug may be temporarily covered with tape to eliminate unnecessary cleaning of the sealing compound. This is especially recommended when dipping plated lugs.

5.512 Any lug used with dry type CEMF cells need not be immersed in one of the above mentioned sealing compounds. R-3126 Silicone Compound is required on the contact surface of all lugs connected to wet or dry type CEMF cells as called for in Section 7E.

Manager, Product Engineering